## NE/SA/SE5212A

#### DESCRIPTION

The NE/SA/SE5212A is a  $14k\Omega$  transimpedance, wideband, low noise differential output amplifier, particularly suitable for signal recovery in fiber optic receivers and in any other applications where very low signal levels obtained from high-impedance sources need to be amplified.

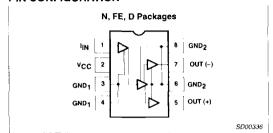
#### **FEATURES**

- Extremely low noise: 2.5pA/√Hz
- Single 5V supply
- Large bandwidth: 140MHz
- Differential outputs
- Low input/output impedances
- 14kΩ differential transresistance
- ESD hardened

#### **APPLICATIONS**

- Fiber-optic receivers, analog and digital
- Current-to-voltage converters

## PIN CONFIGURATION



- Wideband gain block
- Medical and scientific instrumentation
- Sensor preamplifiers
- Single-ended to differential conversion
- Low noise RF amplifiers
- RF signal processing

### ORDERING INFORMATION

DESCRIPTION	TEMPERATURE RANGE	ORDER CODE	DWG #
8-Pin Plastic Dual In-Line Package (DIP)	0 to +70°C	NE5212AN	SOT97-1
8-Pin Plastic Small Outline (SO) Package	0 to +70°C	NE5212AD	SOT96-1
8-Pin Ceramic Dual In-Line Package (DIP)	0 to +70°C	NE5212AFE	0580A
8-Pin Plastic Small Outline (SO) Package	-40°C to +85°C	SA5212AD	SOT96-1
B-Pin Plastic Dual In-Line Package (DIP)	-40°C to +85°C	SA5212AN	SOT97-1
8-Pin Ceramic Dual In-Line Package (DIP)	-40°C to +85°C	SA5212AFE	0580A
8-Pin Plastic Dual In-Line Package (DIP)	-55°C to +125°C	SE5212AN	SOT97-1
8-Pin Ceramic Dual In-Line Package (DIP)	-55°C to +125°C	SE5212AFE	0580A

#### **ABSOLUTE MAXIMUM RATINGS**

SYMBOL	PARAMETER		RATING					
		NE5212A	SA5212A	SE5212A	UNIT			
V <sub>CC</sub>	Power Supply	6	6	6	V			
	Power dissipation, T <sub>A</sub> =25°C (still air) <sup>1</sup>							
_	8-Pin Plastic DIP	1100	1100	1100	mW			
P <sub>D MAX</sub>	8-Pin Plastic SO	750	750	750	mW			
	8-Pin Cerdip	750	750	750	mw			
IN MAX	Maximum input current <sup>2</sup>	5	5	5	mA			
TA	Operating ambient temperature range	0 to 70	-40 to 85	-55 to 125	°C			
TJ	Operating junction	-55 to 150	-55 to 150	-55 to 150	°C			
T <sub>STG</sub>	Storage temperature range	-65 to 150	-65 to 150	-65 to 150	°C			

#### NOTES:

1. Maximum dissipation is determined by the operating ambient temperature and the thermal resistance:

8-Pin Plastic DIP: 110°C/W 8-Pin Plastic SO: 160°C/W

8-Pin Cerdip: 165°C/W

2. The use of a pull-up resistor to V<sub>CC</sub>, for the PIN diode, is recommended

## NE/SA/SE5212A

### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER	RATING	UNIT
V <sub>CC</sub>	Supply voltage range	4.5 to 5.5	V
TA	Ambient temperature ranges		
	NE Grade	0 to +70	°C
	SA Grade	-40 to +85	°C
	SE Grade	-55 to +125	°C
TJ	Junction temperature ranges		
	NE Grade	0 to +90	°C
	SA Grade	-40 to +105	°C
	SE Grade	-55 to +145	°C

### DC ELECTRICAL CHARACTERISTICS

Minimum and Maximum limits apply over operating temperature range at  $V_{CC}$ =5V, unless otherwise specified. Typical data applies at  $V_{CC}$ =5V and  $T_A$ =25°C1.

SYMBOL	DADAMETED	TEST CONDITIONS	NE5212A			SA/SE5212A			UNIT
	PARAMETER	TEST CONDITIONS	Min	Тур	Max	Min	Тур	Max	UNIT
V <sub>IN</sub>	Input bias voltage		0.6	0.8	0.95	0.55	0.8	1.05	V
V <sub>O±</sub>	Output bias voltage		2.8	3.3	3.7	2.5	3.3	3.8	٧
Vos	Output offset voltage				80			120	mV
Icc	Supply current		21	26	32	20	26	33	mA
IOMAX	Output sink/source current		3	4		3	4		mA
lin	Maximum input current (2% linearity)	Test Circuit 6, Procedure 2	±60	±80		±40	±80		μА
IN MAX	Maximum input current overload threshold	Test Circuit 6, Procedure 4	±80	±120		±60	±120		μА

# NOTES:

<sup>1.</sup> As in all high frequency circuits, a supply bypass capacitor should be located as close to the part as possible.

Phillips Semiconductors Product specification

# Transimpedance amplifier (140MHz)

## NE/SA/SE5212A

#### **AC ELECTRICAL CHARACTERISTICS**

Minimum and Maximum limits apply over operating temperature range at V<sub>CC</sub>=5V, unless otherwise specified. Typical data applies at V<sub>CC</sub>=5V and T<sub>A</sub>=25°C<sup>5</sup>.

SYMBOL	DADAMETED	TEST COMPITIONS	NE5212A			SA/SE5212A			
SYMBOL	PARAMETER	TEST CONDITIONS	Min	Тур	Max	Min	Тур	Max	UNIT
R <sub>T</sub>	Transresistance (differential output)	DC tested, R <sub>L</sub> = ∞ Test Circuit 6, Procedure 1	9.8	14	18.2	9.0	14	19	kΩ
R <sub>O</sub>	Output resistance (differential output)	DC tested	14	30	42	14	30	46	Ω
R <sub>T</sub>	Transresistance (single-ended output)	DC tested, R <sub>L</sub> = ∞	4.9	7	9.1	4.5	7	9.5	kΩ
R <sub>O</sub>	Output resistance (single-ended output)	DC tested	7	15	21	7	15	23	Ω
		Test Circuit 1							
		D package,	1					l	
f <sub>3dB</sub>	Bandwidth (-3dB)	T <sub>A</sub> = 25°C	100	140		100	140	<b>I</b>	MHz
	N, FE packages, T <sub>A</sub> = 25°C 100 120 100								
		T <sub>A</sub> = 25°C	100	120		100	120		
R <sub>IN</sub>	Input resistance		75	110	143	70	110	150	Ω
C <sub>IN</sub>	Input capacitance			10	15		10	18	pF
ΔΡ/ΔV	Transresistance power supply sensi- tivity	V <sub>CC</sub> = 5 ±0.5V		9.6			9.6		%/V
ΔR/ΔΤ	Transresistance ambient temperature sensitivity	D package ΔT <sub>A</sub> = T <sub>A MAX</sub> -T <sub>A MIN</sub>		0.05			0.05		%/°C
I <sub>N</sub>	RMS noise current spectral density (referred to input)	Test Circuit 2 f = 10MHz T <sub>A</sub> = 25°C		2.5			2.5		p <b>A</b> /√Hz̄
	Integrated RMS noise current over the	T <sub>A</sub> = 25°C Test Circuit 2 Δf = 50MHz		20			20		
	bandwidth (referred to input) $C_S = 0^1$	Δf = 100MHz		27			27		
ŧ <sub>T</sub>		Δf = 200MHz		40		$\vdash$	40		nA
•		$\Delta f = 50MHz$		22	<del></del>				
	C <sub>S</sub> = 1pF	Δf = 100MHz		32			32	<b>-</b>	
	1 - 1	Δf = 200MHz		52			52		
PSRR	Power supply rejection ratio <sup>2</sup>	Any package DC tested ΔV <sub>CC</sub> = 0.1V Equivalent AC Test Circuit 3	26	33		20	33	-	dB
PSRR	Power supply rejection ratio <sup>2</sup> (ECL configuration)	Any package f = 0.1MHz <sup>1</sup> Test Circuit 4		23			23		dB
V <sub>O MAX</sub>	Maximum differential output voltage swing	R <sub>L</sub> = ∞ Test Circuit 6, Procedure 3	2.4	3.2		1.7	3.2		V <sub>P-P</sub>
VIN MAX	Maximum input amplitude for output duty cycle of 50 ±5%3	Test Circuit 5		325			325		mV <sub>P-P</sub>
t <sub>R</sub>	Rise time for 50mV output signal4	Test Circuit 5		2.0			2.0		ns

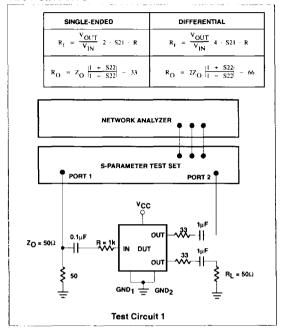
### NOTES:

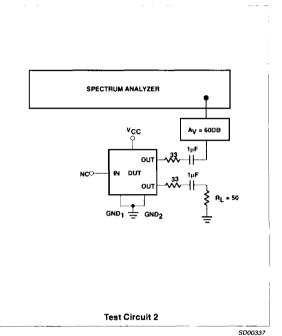
- 1. Package parasitic capacitance amounts to about 0.2pF.
- PSRR is output referenced and is circuit board layout dependent at higher frequencies. For best performance use RF filter in V<sub>CC</sub> line.
- 3. Guaranteed by linearity and over load tests.
- 4. t<sub>R</sub> defined as 20-80% rise time. It is guaranteed by -3dB bandwidth test.
- As in all high frequency circuits, a supply bypass capacitor should be located as close to the part as possible.

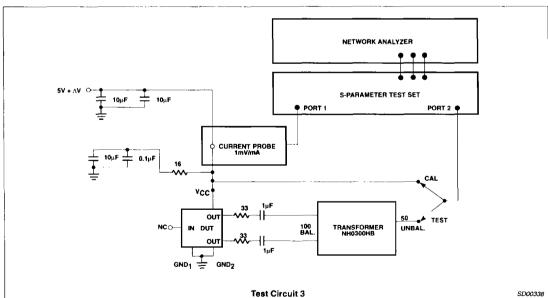
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# NE/SA/SE5212A

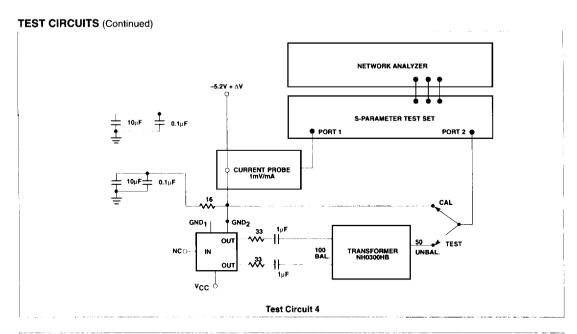
### **TEST CIRCUITS**

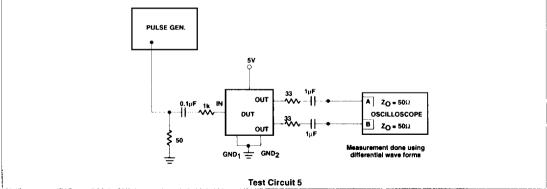






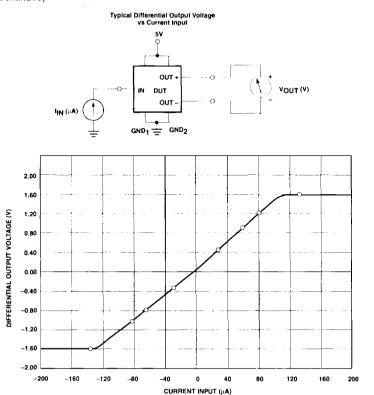
# NE/SA/SE5212A





## NE/SA/SE5212A

## **TEST CIRCUITS (Continued)**



## **NE5212A TEST CONDITIONS**

Procedure 1

RT measured at 30µA

 $\mathsf{R}_\mathsf{T} = (\mathsf{V}_\mathsf{O1} - \mathsf{V}_\mathsf{O2})/(+30\mu\mathsf{A} - (-30\mu\mathsf{A}))$ 

Where: VO1 Measured at I[N = +30](A VO2 Measured at I<sub>IN</sub> = -30μA

Procedure 2 Linearity = 1 - ABS(( $V_{OA} - V_{OB}$ ) / ( $V_{O3} - V_{O4}$ ))

Where: VO3 Measured at IJN = +60µA VO4 Measured at IJN = -60µA

 $V_{OA} = R_T \cdot (+60\mu A) + V_{OB}$ 

V<sub>OB</sub> - R<sub>T</sub> · (- 60µA) + V<sub>OB</sub>

Procedure 3

V<sub>OMAX</sub> = V<sub>O7</sub> - V<sub>O8</sub>

Where: VO7 Measured at I<sub>IN</sub> = +130µA VO8 Measured at I<sub>IN</sub> = ~130µA

Procedure 4

I<sub>IN</sub> Test Pass Conditions:

 $v_{O7}$  –  $v_{O5}$  > 20mV and  $v_{06}$  –  $v_{O5}$  > 20mV Where: VO5 Measured at IJN = +800µA

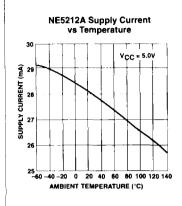
VO6 Measured at I<sub>IN</sub> ≈ -80µA

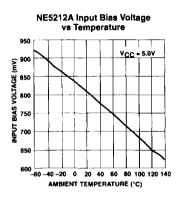
VO7 Measured at I<sub>IN</sub> = +130µA

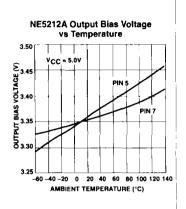
VO8 Measured at I<sub>IN</sub> = ~130μA

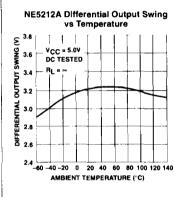
**Test Circuit 8** 

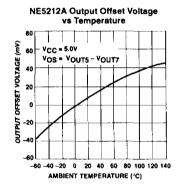
### TYPICAL PERFORMANCE CHARACTERISTICS

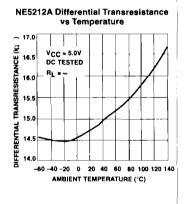


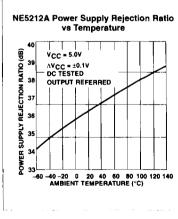


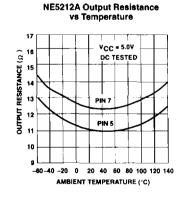


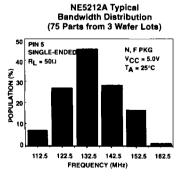






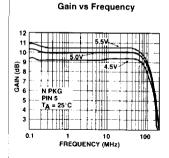


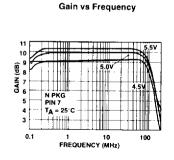


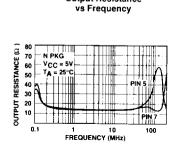


## NE/SA/SE5212A

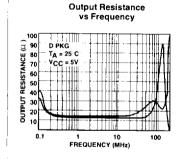
TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

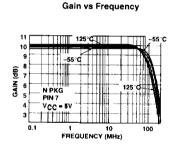


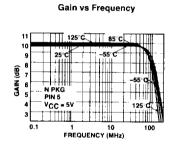


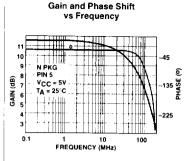


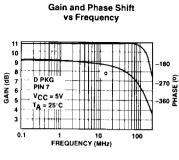
**Output Resistance** 

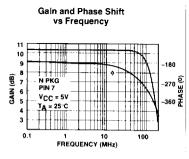




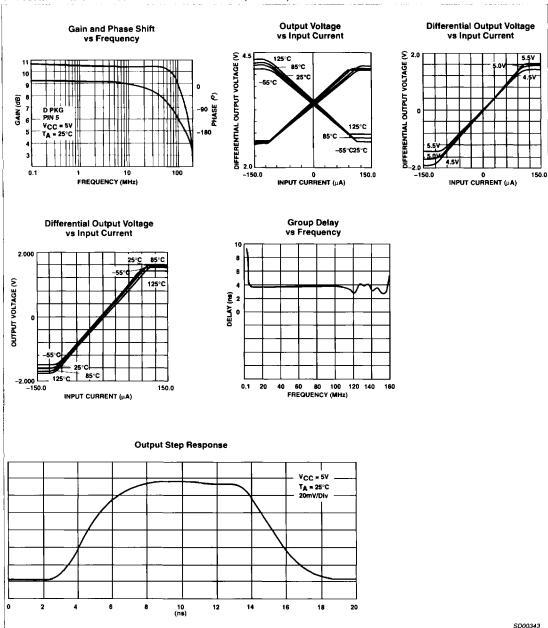








### TYPICAL PERFORMANCE CHARACTERISTICS (Continued)



### NE/SA/SE5212A

### THEORY OF OPERATION

Transimpedance amplifiers have been widely used as the preamplifier in fiber-optic receivers. The NE5212A is a wide bandwidth (typically 140MHz) transimpedance amplifier designed primarily for input currents requiring a large dynamic range, such as those produced by a laser diode. The maximum input current before output stage clipping occurs at typically 240µA. The NE5212A is a bipolar transimpedance amplifier which is current driven at the input and generates a differential voltage signal at the outputs. The forward transfer function is therefore a ratio of the differential output voltage to a given input current with the dimensions of ohms. The main feature of this amplifier is a wideband, low-noise input stage which is desensitized to photodiode capacitance variations. When connected to a photodiode of a few picoFarads, the frequency response will not be degraded significantly. Except for the input stage, the entire signal path is differential to provide improved power-supply rejection and ease of interface to ECL type circuitry. A block diagram of the circuit is shown in Figure 1. The input stage (A1) employs shunt-series feedback to stabilize the current gain of the amplifier. The transresistance of the amplifier from the current source to the emitter of Q3 is approximately the value of the feedback resistor,  $R_F=7k\Omega$ . The gain from the second stage (A2) and emitter followers (A3 and A4) is about two. Therefore, the differential transresistance of the entire amplifier, RT is

$$R_T = \frac{V_{OUT}(diff)}{I_{IN}} = 2R_F = 2(7.2K) = 14.4k\Omega$$

The single-ended transresistance of the amplifier is typically 3.6kΩ.

The simplified schematic in Figure 2 shows how an input current is converted to a differential output voltage. The amplifier has a single input for current which is referenced to Ground 1. An input current from a laser diode, for example, will be converted into a voltage by the feedback resistor  $R_F$ . The transistor Q1 provides most of the open loop gain of the circuit,  $A_{VOL} = 70$ . The emitter follower  $Q_2$  minimizes loading on  $Q_1$ . The transistor  $Q_4$ , resistor  $R_7$ , and  $V_{B1}$  provide level shifting and interface with the  $Q_{15} - Q_{16}$  differential pair of the second stage which is biased with an internal reference,  $V_{B2}$ . The differential outputs are derived from emitter followers  $Q_{11} - Q_{12}$  which are biased by constant current sources. The collectors of  $Q_{11} - Q_{12}$  are bonded to an external pin,  $V_{CC2}$ , in order to reduce the feedback to the input stage. The output impedance is about  $17\Omega$  single-ended. For ease of performance evaluation, a  $33\Omega$  resistor is used in series with each output to match to a  $50\Omega$  test system.

#### **BANDWIDTH CALCULATIONS**

The input stage, shown in Figure 3, employs shunt-series feedback to stabilize the current gain of the amplifier. A simplified analysis can determine the performance of the amplifier. The equivalent input capacitance,  $C_{1N}$ , in parallel with the source,  $I_{S}$ , is approximately 7.5pF, assuming that  $C_{S}\!=\!0$  where  $C_{S}$  is the external source capacitance.

Since the input is driven by a current source the input must have a low input resistance. The input resistance,  $R_{IN}$ , is the ratio of the incremental input voltage,  $V_{IN}$ , to the corresponding input current,  $l_{IN}$  and can be calculated as:

$$R_{IN} = \frac{V_{IN}}{I_{IN}} = \frac{R_F}{1 + A_{VOL}} = \frac{7.2K}{70} = 103\Omega$$

More exact calculations would yield a higher value of  $110\Omega$ .

Thus CIN and RIN will form the dominant pole of the entire amplifier;

$$f_{-3dB} = \frac{1}{2\pi \ R_{IN} \ C_{IN}}$$

Assuming typical values for  $R_F = 7.2k\Omega$ ,  $R_{|N} = 110\Omega$ ,  $C_{|N} = 10pF$ 

$$f_{-3dB} = \frac{1}{2\pi (110) \cdot 10^{-12}} = 145MHz$$

The operating point of Q1, Figure 2, has been optimized for the lowest current noise without introducing a second dominant pole in the pass-band. All poles associated with subsequent stages have been kept at sufficiently high enough frequencies to yield an overall single pole response. Although wider bandwidths have been achieved by using a cascade input stage configuration, the present solution has the advantage of a very uniform, highly desensitized frequency response because the Miller effect dominates over the external photodiode and stray capacitances. For example, assuming a source capacitance of 1pF, input stage voltage gain of 70,  $R_{\rm IN}$  =  $60\Omega$  then the total input capacitance,  $C_{\rm IN}$  = (1+7.5) pF which will lead to only a 12% bandwidth reduction.

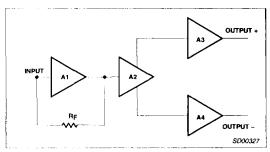


Figure 1. NE5212A - Block Diagram

#### NOISE

Most of the currently installed fiber-optic systems use non-coherent transmission and detect incident optical power. Therefore, receiver noise performance becomes very important. The input stage achieves a low input referred noise current (spectral density) of 3.5 p A/HZ. The transresistance configuration assures that the external high value bias resistors often required for photodiode biasing will not contribute to the total noise system noise. The equivalent input  $_{\text{RMS}}$  noise current is strongly determined by the quiescent current of  $Q_1$ , the feedback resistor  $R_{\text{F}}$  and the bandwidth; however, it is not dependent upon the internal Miller-capacitance. The measured wideband noise was 66nA in a 200MHz bandwidth.

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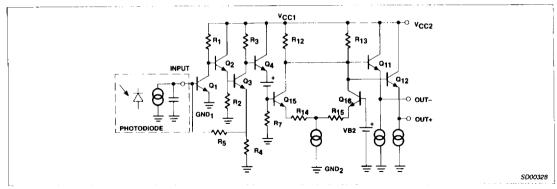


Figure 2. Transimpedance Amplifier

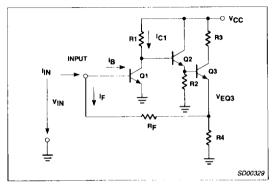


Figure 3. Shunt-Series Input Stage

#### DYNAMIC RANGE

The electrical dynamic range can be defined as the ratio of maximum input current to the peak noise current:

Electrical dynamic range, DE, in a 200MHz bandwidth assuming INMAX = 240µA and a wideband noise of I<sub>FO</sub>=52nA<sub>RMS</sub> for an external source capacitance of C<sub>S</sub> = 1pF.

$$D_E = \frac{\text{(Max. input current)}}{\text{(Peak noise current)}}$$

$$D_E(dB) = 20 \log \frac{(120 \cdot 10^{-6})}{(\sqrt{2} 52nA)}$$

$$\begin{split} D_E(dB) &= 20 \log \frac{(120 \cdot 10^{-6})}{(\sqrt{2} 52 nA)} \\ D_E(dB) &= 20 \log \frac{(120 \mu A)}{(73 nA)} = 64 dB \end{split}$$

In order to calculate the optical dynamic range the incident optical power must be considered.

For a given wavelength λ;

Energy of one Photon =  $\frac{hc}{\lambda}$  watt sec (Joule)

Where h=Planck's Constant = 6.6 × 10<sup>-34</sup> Joule sec.

 $c = speed of light = 3 \times 10^8 \text{ m/sec}$ 

 $c / \lambda = optical frequency$ 

No. of incident photons/sec= where P=optical incident power

No. of incident photons/sec = 
$$\frac{P}{hc}$$

where P = optical incident power

No. of generated electrons/sec = 
$$\frac{P}{\eta}$$
.

where  $\eta$  = quantum efficiency

$$= \frac{\text{no. of generated electron hole paris}}{\text{no. of incident photons}}$$

$$\therefore I = \eta \cdot \frac{\frac{P}{hc}}{\lambda} \cdot \text{e Amps (Coulombs/sec.)}$$

where  $e = electron charge = 1.6 \times 10^{-19}$  Coulombs

Responsivity R = 
$$\frac{\eta \cdot e}{hc}$$
 Amp/watt

Assuming a data rate of 400 Mbaud (Bandwidth, B=200MHz), the noise parameter Z may be calculated as:1

$$Z = \frac{I_{EQ}}{qB} = \frac{52 \cdot 10^{-9}}{(1.6 \cdot 10^{-19})(200 \cdot 10^6)} = 1625 \left(\frac{Amp}{Amp}\right)$$

where Z is the ratio of RMS noise output to the peak response to a single hole-electron pair. Assuming 100% photodetector quantum efficiency, half mark/half space digital transmission, 850nm lightwave and using Gaussian approximation, the minimum required optical power to achieve 10-9 BER is:

$$P_{avMIN} = 12 \frac{hc}{\lambda} B Z = 12 (2.3 \cdot 10^{-19})$$

$$200 \cdot 10^6 \ 1625 = 897 \text{nW} = -30.5 \text{dBm},$$

where h is Planck's Constant, c is the speed of light,  $\lambda$  is the wavelength. The minimum input current to the NE5212A, at this input power is:

$$I_{avMIN} = qP_{avMIN} \frac{\lambda}{hc}$$

$$= \frac{897 \cdot 10^{-9} \cdot 1.6 \cdot 10^{-19}}{2.3 \cdot 10^{-19}}$$

$$= 6240A$$

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Choosing the maximum peak overload current of  $I_{avMAX}$ =120 $\mu$ A, the maximum mean optical power is:

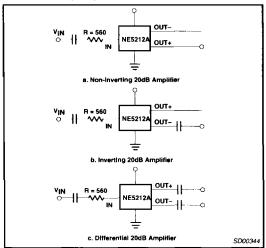


Figure 4. Variable Gain Circuit

$$P_{avMAX} = \frac{hcl_{avMAX}}{\lambda q} = \frac{2.3 \cdot 10^{-19}(120 \cdot 10^{-6})}{1.6 \cdot 10^{-19}}$$
$$= 172\mu W \text{ or } -7.6dBm$$

Thus the optical dynamic range, Do is:

$$D_O = P_{avMAX} - P_{avMIN} = -30.5 - (-7.6) = 22.8 dB.$$

This represents the maximum limit attainable with the NE5212A operating at 200MHz bandwidth, with a half mark/half space digital transmission at 820nm wavelength.

### **APPLICATION INFORMATION**

Package parasitics, particularly ground lead inductances and parasitic capacitances, can significantly degrade the frequency response. Since the NE5212A has differential outputs which can feed back signals to the input by parasitic package or board layout capacitances, both peaking and attenuating type frequency response shaping is possible. Constructing the board layout so that Ground 1 and Ground 2 have very low impedance paths has produced the best results. This was accomplished by adding a ground-plane stripe underneath the device connecting Ground 1, Pins 8-11, and Ground 2, Pins 1 and 2 on opposite ends of the SO14 package. This ground-plane stripe also provides isolation between the output return currents flowing to either V<sub>CC2</sub> or Ground 2 and the input photodiode currents to flowing to Ground 1. Without this ground-plane stripe and with large lead inductances on the board, the part may be unstable and oscillate near 800MHz. The easiest way to realize that the part is not functioning normally is to measure the DC voltages at the outputs. If they are not close to their quiescent values of 3.3V (for a 5V supply), then the circuit may be oscillating. Input pin layout necessitates that the photodiode be physically very close to the input and Ground 1. Connecting Pins 3 and 5 to Ground 1 will tend to shield the input but it will also tend to increase the capacitance on the input and slightly reduce the bandwidth.

As with any high-frequency device, some precautions must be observed in order to enjoy reliable performance. The first of these is the use of a well-regulated power supply. The supply must be capable of providing varying amounts of current without significantly changing the voltage level. Proper supply bypassing requires that a good quality  $0.1\mu F$  high-frequency capacitor be inserted between  $V_{\rm CC1}$  and  $V_{\rm CC2}$ , preferably a chip capacitor, as close to the package pins as possible. Also, the parallel combination of  $0.1\mu F$  capacitors with  $10\mu F$  tantalum capacitors from each supply,  $V_{\rm CC1}$  and  $V_{\rm CC2}$ , to the ground plane should provide adequate decoupling. Some applications may require an RF choke in series with the power supply line. Separate analog and digital ground leads must be maintained and printed circuit board ground plane should be employed whenever possible.

#### **BASIC CONFIGURATION**

A trans resistance amplifier is a current-to-voltage converter. The forward transfer function then is defined as voltage out divided by current in, and is stated in ohms. The lower the source resistance, the higher the gain. The NE5212A has a differential transresistance of 14k $\Omega$  typically and a single-ended transresistance of  $7k\Omega$  typically. The device has two outputs: inverting and non-inverting. The output

voltage in the differential output mode is twice that of the output voltage in the single-ended mode. Although the device can be used without coupling capacitors, more care is required to avoid upsetting the internal bias nodes of the device. Figure 4 shows some basic configurations.

#### **VARIABLE GAIN**

Figure 5 shows a variable gain circuit using the NE5212A and the NE5230 low voltage op amp. This op amp is configured in a non-inverting gain of five. The output drives the gate of the SD210 DMOS FET. The series resistance of the FET changes with this output voltage which in turn changes the gain of the NE5212A. This circuit has a distortion of less than 1% and a 25dB range, from -42.2dBm to -15.9dBm at 50MHz, and a 45dB range, from -60dBm to -14.9dBm at 10MHz with 0 to 1V of control voltage at  $V_{\rm CC}$ .

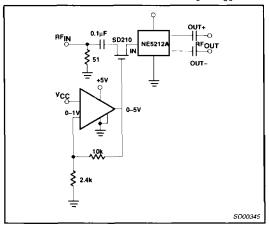


Figure 5. Variable Gain Circuit

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Philips Semiconductors Product specification

# Transimpedance amplifier (140MHz)

## NF/SA/SF5212A

#### 16MHZ CRYSTAL OSCILLATOR

Figure 6 shows a 16MHz crystal oscillator operating in the series resonant mode using the NE5212A. The non-inverting input is fed back to the input of the NE5212A in series with a 2pF capacitor. The output is taken from the inverting output.

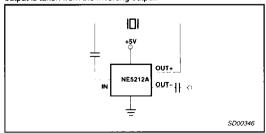


Figure 6. 16MHz Crystal Oscillator

#### DIGITAL FIBER OPTIC RECEIVER

Figures 7 and 8 show a fiber optic receiver using off-the-shelf components.

The receiver shown in Figure 7 uses the NE5212A, the Philips Semiconductors 10116 ECL line receiver, and Philips/Amperex BPF31 PIN diode. The circuit is a capacitor-coupled receiver and utilizes positive feedback in the last stage to provide the hysteresis. The amount of hysteresis can be tailored to the individual application by changing the values of the feedback resistors to maintain the desired balance between noise immunity and sensitivity. At room temperature, the circuit operates at 50Mbaud with a BER of 10E-10 and over the automotive temperature range at 40Mbaud with a BER of 10E-9. Higher speed experimental diodes have been used to operate this circuit at 220Mbaud with a BER of 10E-10.

Figure 8 depicts a TTL receiver using the NE5212A and the NE5214 fast amplifier system along with the Philips/Amperex PIN diode. The system shown is optimized for 50 Mb/s Non Return to Zero (NRZ) data. A link status indication is provided along with a jamming function when the input level is below a user-programmable threshold level.

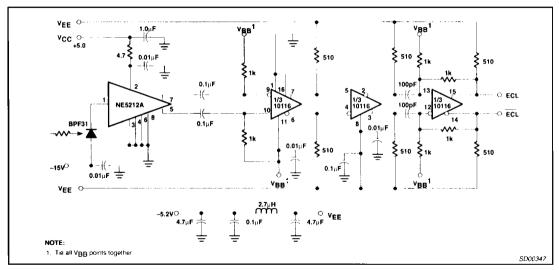


Figure 7. ECL Fiber Optic Receiver

# NE/SA/SE5212A

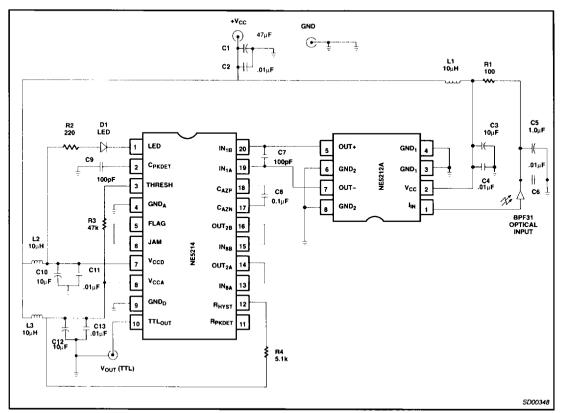


Figure 8. A 50Mb/s TTL Digital Fiber Optic Receiver

## NE/SA/SE5212A

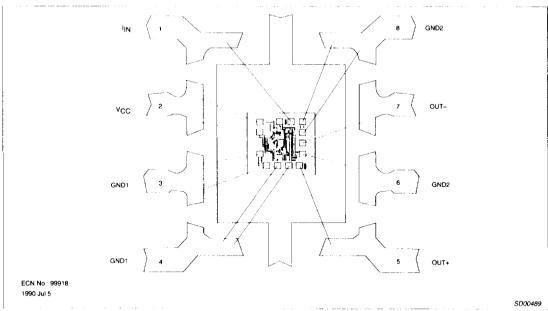


Figure 9. NE/SA/SE5212A Bonding Diagram

#### Die Sales Disclaimer

Due to the limitations in testing high frequency and other parameters at the die level, and the fact that die electrical characteristics may shift after packaging, die electrical parameters are not specified and die are not guaranteed to meet electrical characteristics (including temperature range) as noted in this data sheet which is intended only to specify electrical characteristics for a packaged device.

All die are 100% functional with various parametrics tested at the wafer level, at room temperature only (25°C), and are guaranteed to be 100% functional as a result of electrical testing to the point of wafer sawing only. Although the most modern processes are utilized for wafer sawing and die pick and place into waffle pack

carriers, it is impossible to guarantee 100% functionality through this process. There is no post waffle pack testing performed on individual die.

Since Philips Semiconductors has no control of third party procedures in the handling or packaging of die, Philips Semiconductors assumes no liability for device functionality or performance of the die or systems on any die sales.

Although Philips Semiconductors typically realizes a yield of 85% after assembling die into their respective packages, with care customers should achieve a similar yield. However, for the reasons stated above, Philips Semiconductors cannot guarantee this or any other yield on any die sales.

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